



MARCH 2018



TUV certification is shifting the automotive landscape

MAJEED AHMAD, AUTOMOTIVE CONTRIBUTOR

Why are certifications like ISO 26262 only becoming more prominent now? For a start, the electronic content of vehicles is increasing almost universally.

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The new paradigm for reliable, scalable, affordable SiC semiconductors

RHONDA STRATTON, LITTELFUSE, INC.

The high start-up costs associated with fabricating SiC wafers and the high cost of finished devices (as much as five to ten times more than silicon power devices) means many companies are still cautious about entering the SiC marketplace. This is not surprising. As with any new semiconductor technology, as the technology progresses from early stage to mainstream adoption, manufacturers must create solutions that can reliably produce high-yield wafers at high volumes to achieve affordability.

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Littelfuse 1200 V SiC MOSFETs deliver ultra-low on-resistance

RICH NASS, EMBEDDED COMPUTING DESIGN

The LSIC1MO120E0120 and LSIC1MO120E0160 SiC MOSFETs offer ultra-low on-resistance (RDS(ON)) levels, just 120 and 160 m Ω , respectively. These SiC MOSFETs are designed for use as power semiconductor switches in a wide range of various power conversion systems.

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GaN Systems pushes the envelope with high-current GaN power transistor

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The new power transistor increases the power density to 500 kW, needed for power conversion systems, including automotive traction inverters, very high power on-board chargers (OBC), large-scale energy storage systems, and industrial motor drives.

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TI releases MCU family for cost-sensitive power control applications

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The C2000 F28004x MCUs also feature 60 percent lower active power than previous Piccolo devices; TI's fourth generation of high-resolution PWM timer technology; an embedded real-time analysis and diagnostic unit; an ultra-high-speed serial interface; and flexible boot modes.

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LDRA moves to support AUTOSAR, Mac users

RICH NASS, EMBEDDED COMPUTING DESIGN

At Embedded World 2018, Rich Nass of Embedded Computing Design interviewed Jim McElroy, Vice President of LDRA. McElroy revealed several important automotive announcements from the company, including integration of AUTOSAR and SAE J3061 compliance modules into the LDRA tool suite.

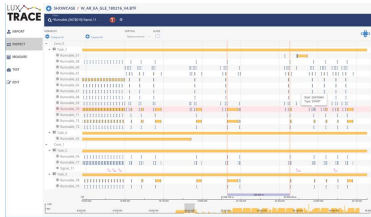
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Renesas 28 nm automotive control MCU integrates 16 MB on-chip flash, up to six CPU cores

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RH850/E2x MCUs incorporate up to six 400 MHz CPU cores and deliver up to 9600 MIPS, which the company claims is the highest performance for an automotive-grade MCU in the industry.

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Luxoft LuxTrace delivers 10x improvement in automotive trace timing analysis

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According to Luxoft, LuxTrace performs large traces up to 10x faster than previous versions, and can be operated by multiple users simultaneously thanks to a centralized server configuration available from the company.

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Bay Trail J1900 P-cap touch-panel PC for in-vehicle applications

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The TAICENN TPC-DCXXC1E series is a low power consumption, fanless, enhanced stability and reliability industrial touch-panel PC product specifically designed for in-vehicle applications.

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